



MATERIALS
RESEARCH
SOCIETY

SYMPOSIUM PROCEEDINGS

Volume 533

Epitaxy and Applications of Si-Based Heterostructures

EDITORS

Eugene A. Fitzgerald

Derek C. Houghton

Patricia M. Mooney

MATERIALS RESEARCH SOCIETY
SYMPOSIUM PROCEEDINGS VOLUME 533

Epitaxy and Applications of Si-Based Heterostructures

Symposium held April 13-17, 1998, San Francisco, California, U.S.A.

EDITORS:

Eugene A. Fitzgerald

*Massachusetts Institute of Technology
Cambridge, Massachusetts, U.S.A.*

Derek C. Houghton

*SiGe Microsystems
Ottawa, Ontario, Canada*

Patricia M. Mooney

*IBM T.J. Watson Research Center
Yorktown Heights, New York, U.S.A.*



Materials Research Society
Warrendale, Pennsylvania

Direct Optical Measurement of the valence band offset of p^+ $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ / p^- Si (100) by Heterojunction Internal Photoemission

C.L. Chang, L.P. Rokhinson, and J.C. Sturm, Department of Electrical Engineering, Center for Photonics and Optoelectronic Materials, Princeton University, Princeton, NJ 08544 USA, cchang@ee.princeton.edu

ABSTRACT

Optical absorption measurements have been performed to study the effect of carbon on the valence band offset of compressively strained p^+ $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ /(100) p^- Si heterojunction internal photoemission structures grown by Rapid Thermal Chemical Vapor Deposition (RTCVD) with substitutional carbon levels up to 2.5%. Results indicated that carbon decreased the valence band offset by 26 ± 1 meV/ %C. Results from optical measurement in this study agreed with previous data from capacitance-voltage measurements. Based on previous reports of carbon effect on the bandgap of compressively strained $\text{Si}_{1-x}\text{Ge}_x$, our work suggests that the effect of carbon incorporation on the band alignment of $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ /Si is to reduce the valence band offset, with a negligible effect on the conduction band alignment.

INTRODUCTION

Strained $\text{Si}_{1-x}\text{Ge}_x$ /Si heterostructures have been extensively studied and have led to many device applications. The advantage of using strained $\text{Si}_{1-x}\text{Ge}_x$ /Si heterostructures results from the flexibility in bandgap engineering by controlling the amount of incorporated Ge into Si matrix. However, due to the 4% larger atomic size of Ge than that of Si, strain involved in $\text{Si}_{1-x}\text{Ge}_x$ prevents one from growing unlimited pseudomorphic $\text{Si}_{1-x}\text{Ge}_x$ layer on Si substrate without introducing misfit dislocations. Recently $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ has attracted a strong interest due to the ability of substitutional C to compensate the strain caused by Ge atoms, with 1% substitutional C compensating the strain caused by 8-10 % Ge¹⁻⁶.

Photoluminescence (PL) measurements on $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ as well as transport studies of heterojunction bipolar transistors (HBT's) with $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ as the base showed that the addition of 1% C increases the bandgap of $\text{Si}_{1-x}\text{Ge}_x$ by 21-26 meV³⁻⁵. However, reducing the strain in $\text{Si}_{1-x}\text{Ge}_x$ by adding C increases the bandgap less than does reducing the strain by merely removing Ge. These results imply that, for a given bandgap, $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ has less misfit strain and therefore allows a greater critical thickness than does $\text{Si}_{1-x}\text{Ge}_x$.

Although it is generally agreed that 1% C increases bandgap by 21~26 meV, it is still under debate regarding how the bandgap increase is allocated in the band alignment of $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ /Si heterostructures. Several electrical and optical methods have been used to determine the band alignment. A temperature-dependent leakage current study on p^+ $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ / p^- Si unipolar diodes indicated that C decreased the valence band offset (ΔE_v) of the resulting $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ /Si heterostructure¹³. However, no accurate quantitative number was extracted due to scatter in data among devices caused by strong dependence of leakage current on local defects. Capacitance-Voltage (C-V) measurements, on the other hand, are theoretically insensitive to anomalous sources of leakage current. They have demonstrated a clear downward trend of ΔE_v of $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ /Si by C incorporation with minimal scatter of data among devices and indicated that

the increase in bandgap by C is fully accommodated in the valence band⁷. Similar results were also obtained from C-V analysis of Si_{1-x-y}Ge_xC_y based metal-oxide-semiconductor structures¹⁴. X-ray photoelectron spectroscopy (XPS) evaluation on the Si_{1-x-y}Ge_xC_y /Si valence band offset did not show significant change with carbon incorporation (with accuracy limit ±30 meV), consistent with the finding that the effect of carbon is small¹⁸.

Conflicting results have also been reported. An indirect evidence from PL study on the Si_{1-x-y}Ge_xC_y / Si_{1-y}C_y quantum wells suggested that C increases ΔE_v of Si_{1-x-y}Ge_xC_y /Si by 10 meV/ %C¹⁵. XPS measurements on Ge-rich Si_{1-x-y}Ge_xC_y indicated an increase in ΔE_v by ~50 meV/%C¹⁹. Moreover, recent results from admittance spectroscopy on Si_{1-x-y}Ge_xC_y/Si multi-quantum wells suggested a large effect by C (~ 80 meV/ %C) on both the conduction and valence band offset of Si_{1-x-y}Ge_xC_y /Si¹⁶. Given conflicting reports, it is therefore necessary to have a direct optical measurement on the Si_{1-x-y}Ge_xC_y /Si heterostructures. In this study, we report such a measurement of the valence band offset by heterojunction internal photoemission (HIP) of Si_{1-x-y}Ge_xC_y / Si (100) from the onset of photocurrent.

EXPERIMENT

The samples in this study contain 39% Ge and up to 2.5% substitutional carbon and were grown by RTCVD⁷. They contain a p⁺ Si buffer for substrate contact, followed by 0.2 μm p⁻ Si, 2 nm undoped Si_{1-x-y}Ge_xC_y spacer and 18 nm p⁺ Si_{1-x-y}Ge_xC_y. Finally, a 20 nm heavily doped (~ 10²⁰/cm³) Si layer was grown for a top contact. Substitutional carbon fractions were measured by X-ray diffraction, assuming 8.3 Ge/C strain compensation ratio. For the rest of this paper, all carbon levels refer to the substitutional levels measured by this method.

Device were fabricated by a simple mesa etching in CF₄/O₂ plasma and Al metallization by lift-off. A device structure is shown in figure 1. Good rectifying characteristics were observed at low temperatures (~ 77K), indicating a significant valence band offset between p⁺ Si_{1-x-y}Ge_xC_y / p⁻ Si. Samples were further cooled down to ~ 4 K to minimize thermionic leakage current for infrared photocurrent measurements and a good ohmic contact was still observed. Optical absorption measurements were performed at 4K using a calibrated glowbar IR source, a spectrometer and phase-sensitive detection.

Figure 2 shows the band diagram of the p⁺ Si_{1-x-y}Ge_xC_y / p⁻ Si HIP structure. Under a reverse bias, holes current is mostly blocked by the valence band offset and the ideal leakage current comes from thermionically emitted holes from p⁺ Si_{1-x-y}Ge_xC_y layer. When infrared light is incident on the p⁺ Si_{1-x-y}Ge_xC_y layer, holes will be excited to higher energy states, and if the photon energy is large enough for hole to overcome the barrier posed by the valence band offset, a photocurrent will result. From the band diagram, ΔE_v can be expressed as

$$\Delta E_v = E_F(\text{SiGeC}) + qV_{bi} + E_F(\text{Si}) \quad (1)$$

where E_F(SiGeC) is the distance between Fermi level and the valence band of Si_{1-x-y}Ge_xC_y, qV_{bi} is the built-in voltage of the junction, E_F(Si) is the distance of the valence band of Si and the Fermi level. Since the Si_{1-x-y}Ge_xC_y is heavily doped, the threshold energy for the onset of photocurrent is E_v - E_F(SiGeC). To extract ΔE_v, one also needs to know the doping concentrations in Si_{1-x-y}Ge_xC_y to know E_F(SiGeC). Doping concentrations were obtained by SIMS measurement on similarly grown samples and SIMS data show no dependence of dopants

(boron) incorporation on the carbon level. We thus assume the onset of photocurrent tracks accurately with ΔE_v .

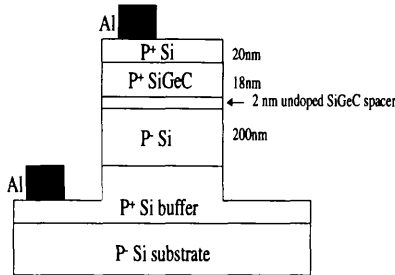


Figure 1: A heterojunction internal photoemission device structure.

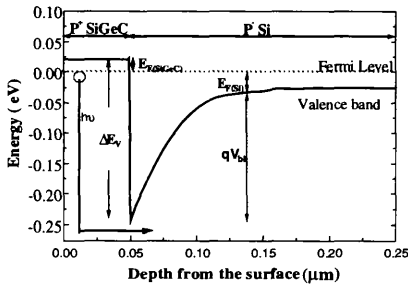


Figure 2: Zero-biased valence band diagram of $p^+ \text{Si}_{1-x-y}\text{Ge}_x\text{C}_y / p^- \text{Si}$.

RESULTS

Figure 3 shows plots of the square root of photoresponse curves as a function of photon energy (Fowler plot) of $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y/\text{Si}$ with different carbon concentrations. The onset of photocurrent decreases as carbon level increases, indicating a decreasing ΔE_v with carbon concentrations. Carbon decreases the ΔE_v of $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y / \text{Si}$ by $26 \pm 1 \text{ meV}/\% \text{C}$, as shown in figure 4. This is consistent with previously reported values measured by C-V measurements^{7,14}, and similar to the increase in bandgap with carbon. We conclude that the increase in bandgap is reflected in the valence band of $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$, with very little or no change in the conduction band. Thus little ΔE_c in $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y / \text{Si}$ (100) is expected as in $\text{Si}_{1-x}\text{Ge}_x/\text{Si}$.

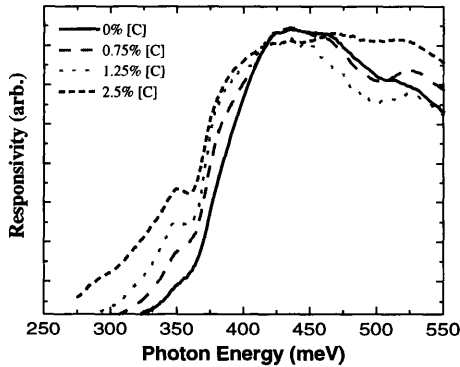


Figure 3: Photoresponse curves of $p^+ \text{Si}_{1-x-y}\text{Ge}_x\text{C}_y / p^- \text{Si}$ as well as $p^+ \text{Si}_{1-x}\text{Ge}_x / p^- \text{Si}$. Samples were measured at 4K.

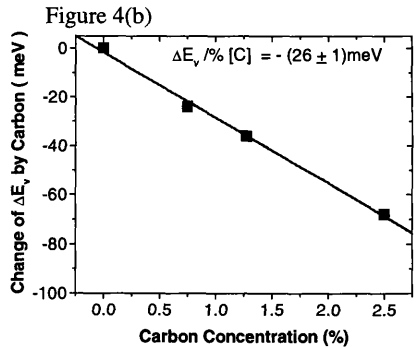
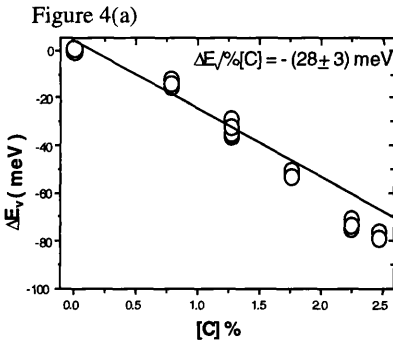


Figure 4: A comparison of change of ΔE_v of $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y / \text{Si}$ as a function of C concentrations. Figure 4(a) is measured by C-V method⁷ and figure 4(b) is the results for HIP measurement, as extracted from figure 2.

Figure 5 shows the valence band offset of $\text{Si}_{1-x}\text{Ge}_x / \text{Si}$ ¹⁸ and $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y / \text{Si}$ as a function of lattice mismatch and equivalent Ge levels for $\text{Si}_{1-x}\text{Ge}_x$ of the given strain. Adding carbon to $\text{Si}_{1-x}\text{Ge}_x$ to form $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ on silicon (100) reduces both ΔE_v and the compressive strain. But compared to strain reduction by reducing the Ge fraction alone, the ΔE_v reduction by adding carbon is small. For example, the valence band offset of $\text{Si}_{0.585}\text{Ge}_{0.39}\text{C}_{0.025} / \text{Si}$ is ~ 100 meV larger than that of an equally strained $\text{Si}_{0.82}\text{Ge}_{0.18} / \text{Si}$ heterostructure. Figure 5 also predicts that,

by extrapolating the dashed line to the vertical axis, a strain-free $\text{Si}_{1.563}\text{Ge}_{0.39}\text{C}_{0.047}/\text{Si}$ heterostructure will have ~ 200 meV valence band offset.

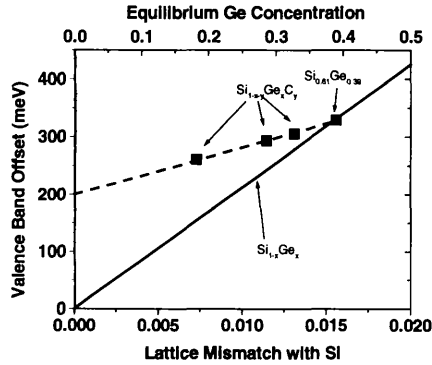


Figure 5: Summary of valence band offsets obtained from optical absorption measurement as a function of lattice mismatch with Si and equivalent Ge concentration. The solid line represents the valence band offsets of $\text{Si}_{1-x}\text{Ge}_x/\text{Si}$.

CONCLUSIONS

In summary, we have studied the valence band offset of compressively strained pseudomorphic $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y/\text{Si}$ (100) by heterojunction internal photomission. Carbon decreased the valence band offset of $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y/\text{Si}$ by 26 ± 1 meV/% carbon. Combining this number with previously reported similar increases in the bandgap caused by carbon, we conclude that the band structure of $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y/\text{Si}$ exhibits a large valence band offset and a negligible conduction band offset, similar to that of $\text{Si}_{1-x}\text{Ge}_x/\text{Si}$ heterostructures.

ACKNOWLEDGEMENTS

The authors like to acknowledge the support by ONR, USAF Rome Lab, and Sandia National Laboratory.

REFERENCES

1. K. Eberl, S.S. Iyer, S. Zollner, J.C. Tsang, and F.K. LeGous, *Appl. Phys. Lett* **60**, 3033 (1992).
2. J.L. Regolini, F. Gisbert, G. Dolino, and P. Boucaud, *Mat. Lett* **18**, 57 (1993).
3. H.J. Osten, H. Rucker, M. Methfessel, E. Bugiel, S. Ruminov, and G. Lippert, *J. Cryst. Growth* **157**, 405 (1995).
4. P. Boucaud, C. Guedj, F. H. Julien, E. Finkman, S. Bodnar, and J.L. Regolini, *Thin Solid Films* **278**, 114 (1996).
5. J. Kolodzey, P. R. Berger, B.A. Orner, D. Hits, F. Chen, A. Khan, X. Shao, M.M. Waite, S. Ismat Shah, C.P. Swann, and K.M. Unruh, *J. Cryst. Growth* **157**, 386 (1995).

6. C.W. Liu, A. St. Amour, J.C. Sturm, Y.R.J. Lacroix, M.L.W. Thewalt, C.W. Magee, and D. Eaglesham, *J. Appl. Phys.* **80**, 3043 (1996).
7. C.L. Chang, A. St. Amour, and J.C. Sturm, *Appl. Phys. Lett* **70**, 1557 (1997).
8. K. Brunner, K. Eberl, and W. Winter, *Phys. Rev. Lett.* **76**, 303, (1996).
9. A. St. Amour, C.W. Liu, J.C. Sturm, Y. Lacroix, and M.L.W. Thewalt, *Appl. Phys. Lett* **67**, 3915 (1995).
10. L.D. Lanzerotti, A. St. Amour, C.W. Liu, and J.C. Sturm, *Elec. Dev. Lett*, **17**, 334 (1996).
11. P. Boucaud, C. Francis, F. Julien, J. Lourtioz, D. Bouchier, S. Bodnar, B. Lambert, and J. Regolini, *Appl. Phys. Lett* **64**, 875(1994).
12. K. Brunner, W. Winter, and K. Eberl, *Appl. Phys. Lett* **69**, 1279 (1996).
13. C.L. Chang, A. St. Amour, L. Lanzerotti, and J.C. Sturm, *Mat. Res. Soc. Sym. Proc.* **402**, 437 (1995)
14. K. Rim, S. Takagi, J.J. Welser, J.L. Hoyt, and J.F. Gibbons, *Mat. Res. Soc. Sym. Proc.*, **379**, 327, (1995).
15. Eberl, K. Brunner, and W. Winter, *European Mat. Res. Soc. Spr Mtg*, Strasbourg, France (1996)
- 16 B.L. Stein, E.T. Yu, E.T. Croke, A.T. Hunter, T. Laursen, A.E. Bair, J.W. Mayer, C.C. Ahn, *Appl. Phys. Lett.*, **70**, 3413 (1997).
- 17 C.L.Chang, S.P. Shukla, W. Pan, V. Venkataraman, J.C. Sturm, and M. Shayegan, 7th International MBE Symposium, Banff, Canada, (1997). Also to appear in *Thin Solid Films*.
- 18 M.Kim and H.J. Osten, *APL*, **70**, 2702 (1997).
19. J. Kolodzey et al, *European Mat. Res. Soc. Spr Mtg*, Strasbourg, France (1996)